

Chip Scale Review

2016 Editorial Calendar

(Editorial close date: 11/20)

January • February

(denotes show distribution)*

Packaging trends	<ul style="list-style-type: none"> • SEMI ISS (Industry Strategy Symposium) Half Moon Bay, CA (Jan 10-13) • SEMI European 3D Summit Grenoble, France (Jan 18-20) * • SMTA Pan Pac Microelectronics Symposium * Kohala Coast, Hawaii (Jan 25-28) • SEMICON Korea Seoul, Korea (January 27-29) • BiTS Workshop * Mesa, AZ (March 6-9) • APEX Expo Las Vegas, NV (March 15-17) • IMAPS Device Packaging (DPC) * Fountain Hills, AZ (March 15-17) • SEMICON China* Productronica China Shanghai China (March 15-17)
Assembly materials	
Advanced underfills for nex-gen flip chip applications	
Wafer carrier solutions	
3D package reliability	
Metrology for 3D integration	
Advances in wafer probing	
Cu TSV stress analysis	
Socket contact technologies	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 22 - Ad Materials Deadline Jan 29

(Editorial close date: 12/19)

March • April

MEMS / sensors roadmap	<ul style="list-style-type: none"> • SEMICON South East Asia Penang, Malaysia (Apr 26-28) • MEPTEC MEMS Technology Symposium * San Jose, CA (TBD) • IoT Symposium * San Jose, CA (TBD) • ECTC * Las Vegas, NV (May 31- June 3)
MEMS in IoT devices	
Flexible substrates	
FOWLP	
Die-to-wafer stacking	
Cu pillar technology	
Packaging of high-power devices	
Glass interposers	
TSV technologies	

Ad Space Close Feb 19 - Materials Close Feb 26

(Editorial close date: 3/11)

May • June

Industry market update	<ul style="list-style-type: none"> • IMAPS Advanced Technology Workshop * Dearborn, MI (TBD) • IEEE/SW Test Workshop (SWTW) San Diego, CA (TBD) • SEMI Europe Packaging Tech Seminar * Porto, Portugal (TBD) • SEMICON West * San Francisco, CA (July 12-14)
Package optimization & failure analysis with 3D X-ray	
Failure analysis methodologies for advanced packaging	
Multi-chip packaging technology advances	
Ultra-thin embedded packaging	
Plasma dicing singulation	
Packaging materials update	
3D integration for tomorrow's devices	
Lithography challenges	

Ad Space Close May 20 - Ad Materials Close May 27